



## ABSTRACT

This document describes the known exceptions to the functional specifications (advisories).

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## 1 Functional Advisories

Advisories that affect the device's operation, function, or parametrics.

✓ The check mark indicates that the issue is present in the specified revision.

Errata Number	Rev A
<a href="#">PORT31</a>	✓
<a href="#">PORT32</a>	✓
<a href="#">PORT34</a>	✓
<a href="#">USCI42</a>	✓
<a href="#">USCI45</a>	✓
<a href="#">USCI47</a>	✓
<a href="#">USCI50</a>	✓
<a href="#">USCI51</a>	✓

## 2 Preprogrammed Software Advisories

Advisories that affect factory-programmed software.

✓ The check mark indicates that the issue is present in the specified revision.

Errata Number	Rev A
<a href="#">UDMA2</a>	✓

## 3 Debug Only Advisories

Advisories that affect only debug operation.

✓ The check mark indicates that the issue is present in the specified revision.

The device does not have any errata for this category.

## 4 Fixed by Compiler Advisories

Advisories that are resolved by compiler workaround. Refer to each advisory for the IDE and compiler versions with a workaround.

✓ The check mark indicates that the issue is present in the specified revision.

The device does not have any errata for this category.

Refer to the following MSP430 compiler documentation for more details about the CPU bugs workarounds.

### TI MSP430 Compiler Tools (Code Composer Studio IDE)

- [MSP430 Optimizing C/C++ Compiler](#): Check the --silicon\_errata option
- [MSP430 Assembly Language Tools](#)

### MSP430 GNU Compiler (MSP430-GCC)

- [MSP430 GCC Options](#): Check -msilicon-errata= and -msilicon-errata-warn= options
- [MSP430 GCC User's Guide](#)

### IAR Embedded Workbench

- [IAR workarounds for msp430 hardware issues](#)

## 5 Nomenclature, Package Symbolization, and Revision Identification

The revision of the device can be identified by the revision letter on the [Package Markings](#) or by the [HW\\_ID](#) located inside the TLV structure of the device.

### 5.1 Device Nomenclature

To designate the stages in the product development cycle, TI assigns prefixes to the part numbers of all MSP MCU devices. Each MSP MCU commercial family member has one of two prefixes: MSP or XMS. These prefixes represent evolutionary stages of product development from engineering prototypes (XMS) through fully qualified production devices (MSP).

**XMS** – Experimental device that is not necessarily representative of the final device's electrical specifications

**MSP** – Fully qualified production device

Support tool naming prefixes:

**X**: Development-support product that has not yet completed Texas Instruments internal qualification testing.

**null**: Fully-qualified development-support product.

XMS devices and X development-support tools are shipped against the following disclaimer:

"Developmental product is intended for internal evaluation purposes."

MSP devices have been characterized fully, and the quality and reliability of the device have been demonstrated fully. TI's standard warranty applies.

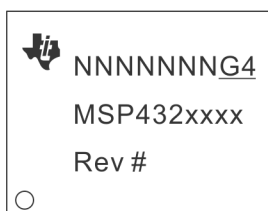
Predictions show that prototype devices (XMS) have a greater failure rate than the standard production devices. TI recommends that these devices not be used in any production system because their expected end-use failure rate still is undefined. Only qualified production devices are to be used.

TI device nomenclature also includes a suffix with the device family name. This suffix indicates the temperature range, package type, and distribution format.

### 5.2 Package Markings

**RGC64**

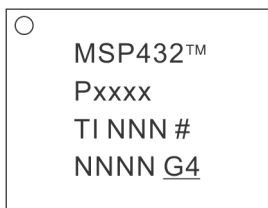
**QFN (RGC), 64 pin**



# = Die revision  
○ = Pin 1 location  
N = Lot trace code

**PZ100**

**LQFP (PZ) 100 Pin**



# = Die revision  
○ = Pin 1 location  
N = Lot trace code

### 5.3 Memory-Mapped Hardware Revision (TLV Structure)

Die Revision	TLV Hardware Revision
Rev A	41h

Further guidance on how to locate the TLV structure and read out the HW\_ID can be found in the device User's Guide.

## 6 Advisory Descriptions

<b>PORT31</b>	<b>PORT Module</b>
<b>Category</b>	Functional
<b>Function</b>	Fast transient noise on GPIOs may result in a constant high current
<b>Description</b>	<p>GPIOs subject to fast transient noise (e.g. electromagnetic noise) may see a high constant current. The constant high current is a result of the fast transient noise triggering the internal ESD protection structure and it persists as long as the internal or external current driver sustains the current.</p> <ol style="list-style-type: none"> <li>1. When using in Input mode (PxDIR = 0 ), all GPIOs are impacted by this issue. A fast transient noise on the pin configured as an input or on an adjacent pin could cause a constant high current that is sustained as long as the external driver is present.</li> <li>2. When using in Output mode (PxDIR = 1), only the high drive GPIOs (P2.0,P2.1,P2.2 and P2.3) are impacted by this issue. If the affected GPIOs are configured in high drive mode (PxDS register) and they (or adjacent pins) are subject to fast transient noise, it could cause a constant high current. Note that this issue is not seen in GPIOs configured in the output direction with the regular drive strength setting since the high drive mode is required to sustain the high current.</li> </ol> <p>If the GPIO configuration is reset by a power cycle, the constant high current is no longer sustained.</p>
<b>Workaround</b>	<ol style="list-style-type: none"> <li>1. For GPIOs configured as input, ensure that they are driven by a current-limited source &lt; 30mA (up to Tj=85C) or 20mA (up to Tj=125C, if allowed for device. See device specific datasheet for maximum allowed operating junction temperature) OR use a series resistance &gt;100 ohm (up to Tj=85C) or 150 ohm (up to Tj=125C, if allowed for device. See device specific datasheet for maximum allowed operating junction temperature) to limit the current.</li> <li>2. For high drive GPIOs configured as output, ensure adequate protection from fast transients is provided to both the high drive IOs and any adjacent pins.</li> <li>3. In general, it is recommended to terminate any unused GPIOs in the output direction, driving low to minimize the occurrence of this issue.</li> <li>4. For guidelines on ESD considerations refer to the document: <a href="#">MSP430 System-level ESD Considerations SLAA530</a></li> </ol>
<b>PORT32</b>	<b>PORT Module</b>
<b>Category</b>	Functional
<b>Function</b>	Successive writes to port registers may cause interrupt to pend incorrectly
<b>Description</b>	<p>Writing to the PxIES register sets the corresponding PxIFG bit. The PxIFG bit can be cleared by writing '0' to it (clearing the register). However if the PxIFG bit is cleared immediately (next instruction cycle) after writing to the PxIES register, the interrupt flag does not clear and stays pending.</p>
<b>Workaround</b>	Insert a NOP or __no_operation(); instruction after writing to the PxIES register and before clearing the PxIFG register.

<b>PORT34</b>	<b><i>PORT Module</i></b>
<b>Category</b>	Functional
<b>Function</b>	Timer_A1 & A2 outputs and EUSCIB3 pins should not be used simultaneously
<b>Description</b>	<p>The following pin functions cannot be simultaneously active on the device at any pin:</p> <ol style="list-style-type: none"> <li>1) TA1.0 and UCB3STE</li> <li>2) TA2.0 and UCB3CLK</li> <li>3) TA2.3 and UCB3SIMO</li> <li>4) TA2.4 and UCB3SOMI</li> </ol> <p>Attempting to use both pin's secondary functions will cause functional conflicts and abnormal behavior of the peripherals. For example, using Timer_A2.3 output will prevent proper operation of EUSCIB3SIMO.</p>
<b>Workaround</b>	None.
<b>UDMA2</b>	<b><i>UDMA Module</i></b>
<b>Category</b>	Software in ROM
<b>Function</b>	UDMA driver library versions < 4.20.00.03 (SimpleLink MSP432P4 SDK versions < 2.10.00.14) do not support use case where increment size and transfer size are different.
<b>Description</b>	UDMA driver library APIs with versions < 4.20.00.03 (SimpleLink MSP432P4 SDK versions < 2.10.00.14) do not support use cases where increment size and transfer sizes are different for either the source or destination. The addresses computation are performed wrongly and this result in erroneous data transfers.
<b>Workaround</b>	<p>This is fixed in driver library API versions &gt;= 4.20.00.03 (SimpleLink MSP432P4 SDK versions &gt;= 2.10.00.14).</p> <ul style="list-style-type: none"> <li>- For TI Drivers users, update to SDK version 2.10.00.14 and TI Drivers based applications automatically leverage the bug fix.</li> <li>- For Driver Library users, update to SDK version 2.10.00.14 and ensure that the application code uses MAP_DMA_ function calls for Driverlib DMA [instead of direct DMA_ API calls].</li> </ul>
<b>USCI42</b>	<b><i>USCI Module</i></b>
<b>Category</b>	Functional
<b>Function</b>	UART asserts UCTXCPITIFG after each byte in multi-byte transmission
<b>Description</b>	UCTXCPTIFG flag is triggered at the last stop bit of every UART byte transmission, independently of an empty buffer, when transmitting multiple byte sequences via UART. The erroneous UART behavior occurs with and without DMA transfer.
<b>Workaround</b>	None.
<b>USCI45</b>	<b><i>USCI Module</i></b>

<b>Category</b>	Functional
<b>Function</b>	Unexpected SPI clock stretching possible when UCxCLK is asynchronous to MCLK
<b>Description</b>	In rare cases, during SPI communication, the clock high phase of the first data bit may be stretched significantly. The SPI operation completes as expected with no data loss. This issue only occurs when the USCI SPI module clock (UCxCLK) is asynchronous to the system clock (MCLK).
<b>Workaround</b>	Ensure that the USCI SPI module clock (UCxCLK) and the CPU clock (MCLK) are synchronous to each other.

## USCI47

### *USCI Module*

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<b>Category</b>	Functional
<b>Function</b>	eUSCI SPI slave with clock phase UCCKPH = 1
<b>Description</b>	<p>The eUSCI SPI operates incorrectly under the following conditions:</p> <ol style="list-style-type: none"> <li>1. The eUSCI_A or eUSCI_B module is configured as a SPI slave with clock phase mode UCCKPH = 1</li> </ol> <p>AND</p> <ol style="list-style-type: none"> <li>2. The SPI clock pin is not at the appropriate idle level (low for UCCKPL = 0, high for UCCKPL = 1) when the UCSWRST bit in the UCxxCTLW0 register is cleared.</li> </ol> <p>If both of the above conditions are satisfied, then the following will occur:  eUSCI_A: the SPI will not be able to receive a byte (UCAxRXBUF will not be filled and UCRXIFG will not be set) and SPI slave output data will be wrong (first bit will be missed and data will be shifted).  eUSCI_B: the SPI receives data correctly but the SPI slave output data will be wrong (first byte will be duplicated or replaced by second byte).</p>
<b>Workaround</b>	<p>Use clock phase mode UCCKPH = 0 for MSP SPI slave if allowed by the application.</p> <p>OR</p> <p>The SPI master must set the clock pin at the appropriate idle level (low for UCCKPL = 0, high for UCCKPL = 1) before SPI slave is reset (UCSWRST bit is cleared).</p> <p>OR</p> <p>For eUSCI_A: to detect communication failure condition where UCRXIFG is not set, check both UCRXIFG and UCTXIFG. If UCTXIFG is set twice but UCRXIFG is not set, reset the MSP SPI slave by setting and then clearing the UCSWRST bit, and inform the SPI master to resend the data.</p>

## USCI50

### *USCI Module*

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<b>Category</b>	Functional
<b>Function</b>	Data may not be transmitted correctly from the eUSCI when operating in SPI 4-pin master mode with UCSTEM = 0
<b>Description</b>	When the eUSCI is used in SPI 4-pin master mode with UCSTEM = 0 (STE pin used as an input to prevent conflicts with other SPI masters), data that is moved into UCxTXBUF

while the UCxSTE input is in the inactive state may not be transmitted correctly. If the eUSCI is used with UCSTEM = 1 (STE pin used to output an enable signal), data is transmitted correctly.

**Workaround** When using the STE pin in conflict prevention mode (UCSTEM = 0), only move data into UCxTXBUF when UCxSTE is in the active state. If an active transfer is aborted by UCxSTE transitioning to the master-inactive state, the data must be rewritten into UCxTXBUF to be transferred when UCxSTE transitions back to the master-active state.

## USCI51

### *USCI Module*

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#### **Category**

Functional

#### **Function**

UART could lose bytes while transmitting with DMA

#### **Description**

Accessing the RXIFG (which is at the same address as the TXIFG) while transmitting with the DMA, could cause a second interrupt for the DMA and overwrite the transmit buffer, before moving to the Shift register.

#### **Workaround**

Clear pending UART RX-interrupt flags with dummy read and enable RX-interrupt as the below example code:

```
volatile uint8 t temp;
temp = EUSCI_A_CMSIS(EUSCI_A2_BASE)->RXBUF;
MAP_UART_enableInterrupt(EUSCI_A2_BASE, EUSCI_A_UART_RECEIVE_INTERRUPT);
```



## 7 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

### Changes from April 24, 2019 to May 17, 2021

**Page**

- Changed the document format and structure; updated the numbering format for tables, figures, and cross references throughout the document.....5

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